



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2019-04-30
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STTH60RQ06W	HTLV*V15Q21I	A	3068	2019-04-30
	Amount	UoM	Unit type	ST ECOPACK Grade
	4400.00	mg	Each	ECOPACK2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	15.75-20.15-5.15	2	Through-hole	
Comment	DO 247			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 23rd November 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.03	Die - Leadframe	234
Lead	14.53	Soft solder	3303

QueryList : REACH-15th January 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	14.53	Soft solder	3303
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	14.53	Soft solder	955047

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	HTLV*V15Q211					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	14.644	mg	supplier	die	Silicon (Si)	7440-21-3		13.952	mg	952771	3171
				supplier	metallization	Aluminium (Al)	7429-90-5		0.234	mg	15980	53
				supplier	Passivation	Silicon Oxide	7631-86-9		0.124	mg	8468	28
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.008	mg	546	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.024	mg	1639	5
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.113	mg	7717	26
Leadframe	M-004 Copper and its alloys	2700.559	mg	supplier	polymer die coating	Probimide	Proprietary		0.189	mg	12879	43
				supplier	alloy	Copper (Cu)	7440-50-8		2696.060	mg	998334	612741
				supplier	alloy	Iron (Fe)	7439-89-6		2.700	mg	1000	614
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.810	mg	300	184
				supplier	metallization	Nickel (Ni)	7440-02-0		0.915	mg	339	208
				supplier	metallization	Phosphorus (P)	7723-14-0		0.074	mg	27	17
Soft solder	Solder	15.216	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	14.532	mg	955047	3303
				supplier	solder	Silver (Ag)	7440-22-4		0.380	mg	24974	86
				supplier	solder	Tin (Sn)	7440-31-5		0.304	mg	19979	69
Bonding wires	M-011 Other inorganic materials	4.925	mg	supplier	wire	Aluminium (Al)	7429-90-5		4.925	mg	1000000	1119
Encapsulation	M-011 Other inorganic materials	1658.459	mg	supplier	mold compound	Silica, vitreous	60676-86-0		1442.859	mg	870000	327923
				supplier	mold compound	Epoxy resin	25068-38-6		165.846	mg	100000	37692
				supplier	mold compound	Phenol resin	29690-82-2		41.462	mg	25000	9423
				supplier	mold compound	Carbon Black	1333-86-4		8.292	mg	5000	1885
Connections coating	Solder	6.197	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.197	mg	1000000	1408